EAST Search History

EAST Search History (Prior Art)

Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	"03070381"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:23
L2	2	"2003183012"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:25
L3	2	"2002120230"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:25
L4	4	"2001088306"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:25
L5	4	"2004114375"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:25
L6	2	"2004165587"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:25
L7	5	"03070381"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:25

L8	2	"7434912".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:28
L9	21767	(freeform near4 fabrication) (stereolithography) (rapid near3 prototyping) (solid near2 fabrication) (solid near2 lithography) (((three near3 dimensional) or 3D) near5 (print\$3 or ink \$4print))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:31
L10	21059	264/401.ccls. (depositing and stacking)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:31
L11	950	L9 and L10	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:31
L12	31	L11 and @pd>"20090630"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:31
L13	786	264/401.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:32
L14	20	L13 and @pd>"20090701"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:32
L16	5122	"s13" and @pd> "20090630"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:41

L17	318	425/174.2.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:41
L18	4	L17 and @pd>"20090630"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 14:41
S1	4	("5736074" "6114187"). PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:05
S2	766	264/401.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:59
S3	7	("20040036200" "20040099983" "20040145088" "20040207123" "20050012247" "6572807" "7120512"). PN. OR ("7329379").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 15:47
S4	178591	(fluid or solvent or resin or polymer or (metal near4 paste)) near7 (eject\$4 or dropping or deposit\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53
S 5	3793762	(substrate or wafer or pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53
S6	83637	S4 and S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53

S7	3139993	(voltage or charage or (electric near4 field) or (electrostatic))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:54
S8	37057	S6 and S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:54
S9	1161081	(nozzle or printhead or ink \$4jet\$4 or stereolithograph \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S10	12179	S8 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S11	157	(solidifying) near5 (S4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S12	0	246/401.ccls. and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:56
S13	314	425/174.2.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:57
S14	20602	(freeform near4 fabrication) (stereolithography) (rapid near3 prototyping) (solid near2 fabrication) (solid near2 lithography) (((three near3 dimensional) or 3D) near5 (print\$3 or ink \$4print))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:43

S15	532063	(solid\$4 near5 (drop\$3 or material or resin))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44
S16	4265	S14 and S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44
S17	349	264/401.ccls. and S16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44
S18	81675	(stack\$4) near6 (droplet or material)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:58
S19	26	S17 and S18	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:58
S20	11	voltage and S19	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:02
S21	2	(nozzle or ink\$4head or ink \$4print) and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:03
S22	10	fluid and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:05

S23	41	("4575330" "4752352" "4863538" "4999143" "5015312" "5058988" "5059021" "5076974" "5104592" "5121329" "5123734" "5133987" "5141680" "5143663" "5174931" "5182056" "5182715" "5184307" "5192469" "5192559" "5204055" "5209878" "5234636" "5238639" "5256340" "5321622" "5597520" "5840239" "5902537" "5902538" "5943235" "5945058" "5965079" "5999184" "6001297").PN. OR	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 17:05
S24	20086	264/401.ccls. (depositing and stacking)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S25	919	S14 and S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S26	246	(solidifying) and S25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S27	766	264/401.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:27
S28	3793762	substrate or wafer or pad	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:27
S29	4999418	AC or DC or (direct near3 curent) or (alternating near3 current) or voltage or electrostatic or (electric near3 field) or (charge)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29

S30	66	S27 and S28 and S29	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29
S31	28	(droplet or solder) and S30	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29
S33	173792	((substrate or wafer or pad) near2 heat\$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:30
S34	3	S31 and S33	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:31
S35	48289	((micro\$4 adj3 needle) or (needle\$2shaped near2 nozzle) printhead print \$2head ink\$3jet stereolithography) same (eject\$4 or dropping or deposit\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 09:35
S36	6251	((micro\$4 adj3 needle) or (needle\$2shaped near2 nozzle) printhead print \$2head ink\$3jet stereolithography) same (eject\$4 or dropping or deposit\$4) same (charges or voltage (electric adj2 field) electrostatic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 09:36
S37	137568	("264").CLAS.	USPAT; USOCR	OR	OFF	2009/12/26 09:37
S38	25	S36 and S37	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 09:37
S39	67720	("118").CLAS.	USPAT; USOCR	OR	OFF	2009/12/26 09:43

S40	23	S39 and S36	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 09:43
S41	76	("2985939" "3868267" "3999188" "4122458" "4129875" "4158204" "4247508" "4294805" "4420446" "4575330" "4636341" "4642653" "4665492" "4675216" "4791022" "4791434" "4818562" "4863538" "4929402" "4935055" "5016683" "5053090" "5059266" "5121329" "5136515" "5147587" "5204055").PN. OR ("5807437").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/12/26 09:47
S42	10636	(nozzle or printhead or ink \$4jet\$4 or stereolithograph \$4) near2 (charges or voltage or electrostatic or (electric adj2 field))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 09:50
S43	4	S42 and S41	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 09:51
S44	498	((nozzle printhead or ink \$4jet\$4 or stereolithograph \$4) adj3 diameter) same (micrometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 09:59
S45	7	"670313".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:32
S46	2	"6780313".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:32

S47	180	((nozzle printhead or ink \$4jet\$4 or stereolithograph \$4) adj3 diameter) same (micrometer same size\$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:33
S48	3312	(electrode) adj (nozzle printhead jet or inkjet or ink \$2jet)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:51
S50	104663	("425").CLAS.	USPAT; USOCR	OR	OFF	2009/12/26 10:52
S51	137568	("264").CLAS.	USPAT; USOCR	OR	OFF	2009/12/26 10:52
S52	13	S48 and (S50 S51)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:52
S53	7816	(electrode) adj2 (nozzle printhead jet or inkjet or ink \$2jet)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:53
S54	11922	(electrode) near2 (nozzle printhead jet or inkjet or ink \$2jet)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:53
S55	19664	(jetting depositng spraying) same (droplets)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:54
S56	23949	(jetting depositing spraying) same (droplets)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:54
S57	669	S54 and S56	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 10:54

S58	5	"02086924"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 11:27
S59	2		US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 11:40
S60	69	(electrode) adj (inside within) adj nozzle	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/26 11:41

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12/26/2009 2:42:30 PM

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